

Gold Plating

Through our surface treatment technology and results,
Create new values.



Gold plating is widely used across electronics, precision devices, medical equipment, and decorative applications due to its excellent electrical conductivity, corrosion resistance, and premium appearance. As products continue to demand higher performance and reliability, selecting the appropriate type of gold plating has become increasingly important. ERG offers two types of hard gold plating and gold-nickel plating, along with prototyping support for electroless gold plating. We provide flexible solutions tailored to product specifications and operating environments, including film thickness, hardness, adhesion, and appearance requirements. Our capabilities enable seamless support from prototyping through mass production.

ERG's gold plating



Plating Type	Gold Purity	Alloy Component	Hardness (HV)	Main Applications	Features
Hard Gold Plating Type A	99.7-99.99%	Co	Approx. 160-210	Contact Parts Wire Bonding	Flexibility; Excellent Conductivity; Good Solderability
Hard Gold Plating Type B	97-98%	Co	Approx. 250-300	Contact Parts Switches	Wear Resistance; Long-Term Reliability
Gold-Nickel Plating	99%	Ni	Approx. 280-350	Sliding Contacts Wear Parts	High Hardness; Tarnish Resistance
Electroless Gold Plating	99% or higher	Please inquire	Please inquire	Micro Electrodes UBM Formation	Uniformity; Suitable for Complex Shapes; No Current Required

We can accommodate both with and without underplating.

● With Underplating

Applying an underplating process according to the application and base material enhances the adhesion, corrosion resistance, and appearance quality of gold plating.

- Copper Underplating: High conductivity, well-suited for thick gold plating.
- Nickel Underplating: Excellent adhesion and smoothness, ideal for electronic and precision components.
- Electroless Nickel Underplating: Applicable to complex shapes and non-conductive substrates.
- Olympic Plating (Copper + Silver Underplating): Special-purpose multilayer structure of Cu → Ag → Au.

● Without Underplating

Gold plating can also be directly applied without underplating.

Suitable for micro-components and special shapes.

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